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CONTACT STRUCTURE OF CAMERA MODULE AND ELECTRONIC DEVICE COMPRISING SAME

Abstract

An electronic device is provided according to various embodiments of the present disclosure. The electronic device includes a housing including a rear plate having an opening and a support bracket at least partially disposed along an edge of the rear plate; a camera decoration disposed in the opening to be exposed to the outside, covering a camera assembly and connected to rear plate; a printed circuit board disposed in the housing; a rear structure supporting the camera assembly and the printed circuit board; a fixing member coupled to the rear structure and fixing the camera assembly and/or the printed circuit board to the support bracket; and a conductive member at least partially disposed between the camera decoration and the fixing member to electrically connect the camera decoration and the fixing member to each other.

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Background/Summary

CROSS-REFERENCE TO RELATED APPLICATION(S) [0001] This application is a continuation application of US Application No.: Ser. No. 18/184,282, filed on Mar. 15, 2023, claiming priority under § 365(c), of PCT International Application No. PCT/KR2021/012720, filed on Sep. 16, 2021, which is based on and claims the benefit of Korean patent application number 10-2021-0045019, filed on Apr. 7, 2021, and Korean patent application number 10-2020-0122096, filed on Sep. 22, 2020, in the Korean Intellectual Property Office, the disclosures of which are incorporated by reference herein in their entireties.

TECHNICAL FIELD

[0002] Various embodiments of the disclosure relate to a contact structure of a camera module for improving an electrostatic discharge (ESD) and an electronic device comprising the camera module.

BACKGROUND ART

[0003] Due to recent remarkable developments in information communication and semiconductor technologies, the dissemination and utilization of various electronic devices are rapidly increasing. In particular, recent electronic devices have been developed to enable communication while being carried.

[0004] Electronic devices may refer to devices that perform specific functions based on embedded programs, such as home appliances, electronic notes, portable multimedia players (PMPs), mobile communication terminals, tablet personal computers (PCs), video/audio devices, desktop/laptop computers, vehicle navigation systems, and so forth. For example, these electronic devices may output stored information in the form of sound or images. With the increasing integration of electronic devices and the common use of ultra-high-speed and large-volume wireless communication, various functions have recently come to be provided in a single electronic device, such as a mobile communication terminal. For example, various functions such as an entertainment function such as gaming, a multimedia function such as music/video playback, a communication and security function for mobile banking, and a function such as a schedule management or electronic wallet, as well as a communication function have been integrated into a single electronic device. Such an electronic device becomes increasingly more compact so that the user can conveniently carry it.

DETAILED DESCRIPTION OF THE DISCLOSURE

Technical Problem

[0005] In an electronic device, a camera module needs to be designed to restrict malfunction due to

static electricity generated from the outside. The camera module may include a camera assembly, and a camera deco for covering the camera assembly. As a general electronic device has been designed such that a contact member (e.g., gasket sponge) is used as a surface mount device (SMD) on a printed circuit board positioned around the camera deco of the camera module, and the contact member directly contacts the camera deco, it was possible to prevent malfunction due to static electricity generated from the outside.

[0006] However, the structure of the contact member described above imposes limits on securing a mounting space in the electronic device, as the contact member has to be disposed on an area of the printed circuit board that overlaps (or faces) the camera deco. The above structure of the contact member may be difficult to maintain an appropriate contact point depending on characteristics such as a type and property of the contact member located in a gap between the camera deco and the printed circuit board.

[0007] According to an embodiment of the disclosure, it is possible to implement a contact structure between a camera deco and a surrounding metal structure by using a fixing member (e.g., a fastening structure) for fixing a camera assembly and/or a printed circuit board to an electronic device. Accordingly, it is possible to provide an improved electrostatic discharge (ESD) by securing a mounting space in the electronic device and having a fixed contact structure.

Technical Solution

[0008] An electronic device according to various embodiments of the disclosure may include a housing including a rear plate including an opening and a support bracket at least partially disposed along an edge of the rear plate; a camera deco disposed in the opening to be exposed to the outside, the camera deco covering a camera assembly and connected to the rear plate; a printed circuit board disposed in the housing; a rear structure supporting the camera assembly and the printed circuit board; a fixing member coupled to the rear structure and fixing the camera assembly and/or the printed circuit board to the support bracket; and a conductive member at least partially disposed between the camera deco and the fixing member to electrically connect the camera deco and the fixing member.

[0009] An electronic device according to various embodiments of the disclosure may include a housing including a rear plate including an opening and a camera deco disposed in the opening to be exposed to the outside and connected to the rear plate; a support bracket disposed in the housing; a printed circuit board disposed on an area of the support bracket; a camera assembly covered by the camera deco and configured to capture an external object through at least one opening formed in the camera deco; a fixing member for fixing the camera assembly and/or the printed circuit board to the support bracket; and a conductive member which is at least partially disposed between the camera deco and the fixing member to electrically connect the camera deco and the fixing member.

Advantageous Effects

[0010] According to various embodiments of the disclosure, a fixing member (e.g., a fastening structure) present for fixing a camera assembly and a printed circuit board may be utilized as a contact structure of a camera module. Accordingly, the fixing member may form a discharge path between a camera deco and a printed circuit board for improving electrostatic discharge (ESD).

[0011] According to various embodiments of the disclosure, the contact structure of the camera module may be implemented by a contact point between a conductive member positioned on a camera deco and a fixing member positioned on a support bracket. Since the conductive member does not require a separate mounting space to be disposed on the printed circuit board, a degree of freedom in design of the electronic device may be secured.

[0012] According to various embodiments of the disclosure, the contact structure of the camera module does not form separate thickness in the electronic device as the conductive member for improving the ESD is mounted inside the camera deco, and thus it is possible to save material costs according to improvement (e.g., reduction) in material and size.

[0013] The effects obtainable from the disclosure are not limited to the effects as described above, and other effects not described above will be clearly understood by a person skilled in the art, to which the disclosure belongs, from the following description.

Description

DESCRIPTION OF THE DRAWINGS

[0014] FIG. 1 is a block diagram illustrating an electronic device in a network environment according to various embodiments;

[0015] FIG. 2 is a front perspective view illustrating an electronic device according to various embodiments of the disclosure;

[0016] FIG. 3 is a rear perspective view illustrating an electronic device according to various embodiments of the disclosure;

[0017] FIG. 4 is an exploded perspective view illustrating an electronic device according to various embodiments of the disclosure;

[0018] FIG. 5 is an exploded perspective view illustrating a support bracket, a rear plate, and a camera deco connected to the rear plate in an electronic device, according to one of various embodiments of the disclosure;

[0019] FIG. 6 is an exploded perspective view enlarging area A of FIG. 5;

[0020] FIG. 7 is a view illustrating a support bracket and a rear structure coupled on the support bracket in a state in which the rear plate of the electronic device is removed, according to one of various embodiments of the disclosure;

[0021] FIG. 8A is a view illustrating a side of the camera deco viewed in one direction, according to one of various embodiments of the disclosure;

[0022] FIG. 8B is a view illustrating another side of a camera deco viewed in another direction, according to one of various embodiments of the disclosure;

[0023] FIG. 9 is a view illustrating a support bracket and a rear structure coupled on the support bracket in an electronic device, viewed by projecting a rear plate, according to one of various embodiments of the disclosure;

[0024] FIG. 10 is an enlarged projection view of area B of FIG. 9; and

[0025] FIG. 11 is a cross-sectional view taken along line L-L' of FIG. 10.

MODE FOR CARRYING OUT THE INVENTION

[0026] FIG. 1 is a block diagram illustrating an electronic device in a network environment according to various embodiments of the disclosure.

[0027] Referring to FIG. 1, the electronic device **101** in the network environment **100** may communicate with an electronic device **102** via a first network **198** (e.g., a short-range wireless communication network), or an electronic device **104** or a server **108** via a second network **199** (e.g., a long-range wireless communication network). According to an embodiment, the electronic device **101** may communicate with the electronic device **104** via the server **108**. According to an embodiment, the electronic device **101** may include a processor **120**, memory **130**, an input device **150**, a sound output device **155**, a display device **160**, an audio module **170**, a sensor module **176**, an interface **177**, a connecting terminal **178**, a haptic module **179**, a camera module **180**, a power management module **188**, a battery **189**, a communication module **190**, a subscriber identification module (SIM) **196**, or an antenna module **197**. In some embodiments, at least one (e.g., the connecting terminal **178**) of the components may be omitted from the electronic device **101**, or one or more other components may be added in the electronic device **101**. According to an embodiment, some (e.g., the sensor module **176**, the camera module **180**, or the antenna module **197**) of the components may be integrated into a single component (e.g., the display device **160**). [0028] The processor **120** may execute, for example, software (e.g., a program **140**) to control at

least one other component (e.g., a hardware or software component) of the electronic device **101** coupled with the processor **120**, and may perform various data processing or computation. According to an embodiment, as at least part of the data processing or computation, the processor **120** may store a command or data received from another component (e.g., the sensor module **176** or the communication module **190**) in volatile memory **132**, process the command or the data stored in the volatile memory **132**, and store resulting data in non-volatile memory **134**. According to an embodiment, the processor **120** may include a main processor **121** (e.g., a central processing unit (CPU) or an application processor (AP)), or an auxiliary processor **123** (e.g., a graphics processing unit (GPU), a neural processing unit (NPU), an image signal processor (ISP), a sensor hub processor, or a communication processor (CP)) that is operable independently from, or in conjunction with, the main processor **121**. For example, when the electronic device **101** includes the main processor **121** and the auxiliary processor **123**, the auxiliary processor **123** may be configured to use lower power than the main processor **121** or to be specified for a designated function. The auxiliary processor **123** may be implemented as separate from, or as part of the main processor **121**.

[0029] The auxiliary processor **123** may control at least some of functions or states related to at least one component (e.g., the display device **160**, the sensor module **176**, or the communication module **190**) among the components of the electronic device **101**, instead of the main processor **121** while the main processor **121** is in an inactive (e.g., sleep) state, or together with the main processor **121** while the main processor **121** is in an active state (e.g., executing an application). According to an embodiment, the auxiliary processor **123** (e.g., an image signal processor or a communication processor) may be implemented as part of another component (e.g., the camera module **180** or the communication module **190**) functionally related to the auxiliary processor **123**. According to an embodiment, the auxiliary processor **123** (e.g., the neural processing unit) may include a hardware structure specified for artificial intelligence model processing. The artificial intelligence model may be generated via machine learning. Such learning may be performed, e.g., by the electronic device **101** where the artificial intelligence is performed or via a separate server (e.g., the server **108**). Learning algorithms may include, but are not limited to, e.g., supervised learning, unsupervised learning, semi-supervised learning, or reinforcement learning. The artificial intelligence model may include a plurality of artificial neural network layers. The artificial neural network may be a deep neural network (DNN), a convolutional neural network (CNN), a recurrent neural network (RNN), a restricted Boltzmann machine (RBM), a deep belief network (DBN), a bidirectional recurrent deep neural network (BRDNN), deep Q-network or a combination of two or more thereof but is not limited thereto. The artificial intelligence model may, additionally or alternatively, include a software structure other than the hardware structure.

[0030] The memory **130** may store various data used by at least one component (e.g., the processor **120** or the sensor module **176**) of the electronic device **101**. The various data may include, for example, software (e.g., the program **140**) and input data or output data for a command related thereto. The memory **130** may include the volatile memory **132** or the non-volatile memory **134**.

[0031] The program **140** may be stored in the memory **130** as software, and may include, for example, an operating system (OS) **142**, middleware **144**, or an application **146**.

[0032] The input device **150** may receive a command or data to be used by another component (e.g., the processor **120**) of the electronic device **101**, from the outside (e.g., a user) of the electronic device **101**. The input device **150** may include, for example, a microphone, a mouse, a keyboard, keys (e.g., buttons), or a digital pen (e.g., a stylus pen).

[0033] The sound output device **155** may output sound signals to the outside of the electronic device **101**. The sound output device **155** may include, for example, a speaker or a receiver. The speaker may be used for general purposes, such as playing multimedia or playing record. The receiver may be used for receiving incoming calls. According to an embodiment, the receiver may be implemented as separate from, or as part of the speaker.

[0034] The display device **160** may visually provide information to the outside (e.g., a user) of the electronic device **101**. The display device **160** may include, for example, a display, a hologram device, or a projector and control circuitry to control a corresponding one of the display, hologram device, and projector. According to an embodiment, the display device **160** may include a touch sensor configured to detect a touch, or a pressure sensor configured to measure the intensity of a force generated by the touch.

[0035] The audio module **170** may convert a sound into an electrical signal and vice versa. According to an embodiment, the audio module **170** may obtain the sound via the input device **150**, or output the sound via the sound output device **155** or a headphone of an external electronic device (e.g., an electronic device **102**) directly (e.g., wiredly) or wirelessly coupled with the electronic device **101**.

[0036] The sensor module **176** may detect an operational state (e.g., power or temperature) of the electronic device **101** or an environmental state (e.g., a state of a user) external to the electronic device **101**, and then generate an electrical signal or data value corresponding to the detected state. According to an embodiment, the sensor module **176** may include, for example, a gesture sensor, a gyro sensor, an atmospheric pressure sensor, a magnetic sensor, an acceleration sensor, a grip sensor, a proximity sensor, a color sensor, an infrared (IR) sensor, a biometric sensor, a temperature sensor, a humidity sensor, or an illuminance sensor.

[0037] The interface **177** may support one or more specified protocols to be used for the electronic device **101** to be coupled with the external electronic device (e.g., the electronic device **102**) directly (e.g., wiredly) or wirelessly. According to an embodiment, the interface **177** may include, for example, a high definition multimedia interface (HDMI), a universal serial bus (USB) interface, a secure digital (SD) card interface, or an audio interface.

[0038] A connecting terminal **178** may include a connector via which the electronic device **101** may be physically connected with the external electronic device (e.g., the electronic device **102**). According to an embodiment, the connecting terminal **178** may include, for example, a HDMI connector, a USB connector, a SD card connector, or an audio connector (e.g., a headphone connector).

[0039] The haptic module **179** may convert an electrical signal into a mechanical stimulus (e.g., a vibration or motion) or electrical stimulus which may be recognized by a user via his tactile sensation or kinesthetic sensation. According to an embodiment, the haptic module **179** may include, for example, a motor, a piezoelectric element, or an electric stimulator.

[0040] The camera module **180** may capture a still image or moving images. According to an embodiment, the camera module **180** may include one or more lenses, image sensors, image signal processors, or flashes.

[0041] The power management module **188** may manage power supplied to the electronic device **101**. According to an embodiment, the power management module **188** may be implemented as at least part of, for example, a power management integrated circuit (PMIC).

[0042] The battery **189** may supply power to at least one component of the electronic device **101**. According to an embodiment, the battery **189** may include, for example, a primary cell which is not rechargeable, a secondary cell which is rechargeable, or a fuel cell.

[0043] The communication module **190** may support establishing a direct (e.g., wired) communication channel or a wireless communication channel between the electronic device **101** and the external electronic device (e.g., the electronic device **102**, the electronic device **104**, or the server **108**) and performing communication via the established communication channel. The communication module **190** may include one or more communication processors that are operable independently from the processor **120** (e.g., the application processor (AP)) and supports a direct (e.g., wired) communication or a wireless communication. According to an embodiment, the communication module **190** may include a wireless communication module **192** (e.g., a cellular communication module, a short-range wireless communication module, or a global navigation

satellite system (GNSS) communication module) or a wired communication module **194** (e.g., a local area network (LAN) communication module or a power line communication (PLC) module). A corresponding one of these communication modules may communicate with the external electronic device **104** via a first network **198** (e.g., a short-range communication network, such as Bluetooth™, wireless-fidelity (Wi-Fi) direct, or infrared data association (IrDA)) or a second network **199** (e.g., a long-range communication network, such as a legacy cellular network, a 5G network, a next-generation communication network, the Internet, or a computer network (e.g., local area network (LAN) or wide area network (WAN))). These various types of communication modules may be implemented as a single component (e.g., a single chip), or may be implemented as multi components (e.g., multi chips) separate from each other. The wireless communication module **192** may identify or authenticate the electronic device **101** in a communication network, such as the first network **198** or the second network **199**, using subscriber information (e.g., international mobile subscriber identity (IMSI)) stored in the subscriber identification module **196**. [0044] The wireless communication module **192** may support a 5G network, after a 4G network, and next-generation communication technology, e.g., new radio (NR) access technology. The NR access technology may support enhanced mobile broadband (eMBB), massive machine type communications (mMTC), or ultra-reliable and low-latency communications (URLLC). The wireless communication module **192** may support a high-frequency band (e.g., the mmWave band) to achieve, e.g., a high data transmission rate. The wireless communication module **192** may support various technologies for securing performance on a high-frequency band, such as, e.g., beamforming, massive multiple-input and multiple-output (massive MIMO), full dimensional MIMO (FD-MIMO), array antenna, analog beam-forming, or large scale antenna. The wireless communication module **192** may support various requirements specified in the electronic device **101**, an external electronic device (e.g., the electronic device **104**), or a network system (e.g., the second network **199**). According to an embodiment, the wireless communication module **192** may support a peak data rate (e.g., 20 Gbps or more) for implementing eMBB, loss coverage (e.g., 164 dB or less) for implementing mMTC, or U-plane latency (e.g., 0.5 ms or less for each of downlink (DL) and uplink (UL), or a round trip of 1 ms or less) for implementing URLLC.

[0045] The antenna module **197** may transmit or receive a signal or power to or from the outside (e.g., the external electronic device). According to an embodiment, the antenna module **197** may include one antenna including a radiator formed of a conductor or conductive pattern formed on a substrate (e.g., a printed circuit board (PCB)). According to an embodiment, the antenna module **197** may include a plurality of antennas (e.g., an antenna array). In this case, at least one antenna appropriate for a communication scheme used in a communication network, such as the first network **198** or the second network **199**, may be selected from the plurality of antennas by, e.g., the communication module **190**. The signal or the power may then be transmitted or received between the communication module **190** and the external electronic device via the selected at least one antenna. According to an embodiment, other parts (e.g., radio frequency integrated circuit (RFIC)) than the radiator may be further formed as part of the antenna module **197**.

[0046] According to various embodiments, the antenna module **197** may form a mmWave antenna module. According to an embodiment, the mmWave antenna module may include a printed circuit board, a RFIC disposed on a first surface (e.g., the bottom surface) of the printed circuit board, or adjacent to the first surface and capable of supporting a designated high-frequency band (e.g., the mmWave band), and a plurality of antennas (e.g., array antennas) disposed on a second surface (e.g., the top or a side surface) of the printed circuit board, or adjacent to the second surface and capable of transmitting or receiving signals of the designated high-frequency band.

[0047] At least some of the above-described components may be coupled mutually and communicate signals (e.g., commands or data) therebetween via an inter-peripheral communication scheme (e.g., a bus, general purpose input and output (GPIO), serial peripheral interface (SPI), or mobile industry processor interface (MIPI)).

[0048] According to an embodiment, commands or data may be transmitted or received between the electronic device **101** and the external electronic device **104** via the server **108** coupled with the second network **199**. The external electronic devices **102** or **104** each may be a device of the same or a different type from the electronic device **101**. According to an embodiment, all or some of operations to be executed at the electronic device **101** may be executed at one or more of the external electronic devices **102**, **104**, or **108**. For example, if the electronic device **101** should perform a function or a service automatically, or in response to a request from a user or another device, the electronic device **101**, instead of, or in addition to, executing the function or the service, may request the one or more external electronic devices to perform at least part of the function or the service. The one or more external electronic devices receiving the request may perform the at least part of the function or the service requested, or an additional function or an additional service related to the request and transfer an outcome of the performing to the electronic device **101**. The electronic device **101** may provide the outcome, with or without further processing of the outcome, as at least part of a reply to the request. To that end, a cloud computing, distributed computing, mobile edge computing (MEC), or client-server computing technology may be used, for example. The electronic device **101** may provide ultra-low-latency services using, e.g., distributed computing or mobile edge computing. In another embodiment, the external electronic device **104** may include an internet-of-things (IoT) device. The server **108** may be an intelligent server using machine learning and/or a neural network. According to an embodiment, the external electronic device **104** or the server **108** may be included in the second network **199**. The electronic device **101** may be applied to intelligent services (e.g., smart home, smart city, smart car, or health-care) based on 5G communication technology or IoT-related technology.

[0049] An electronic device according to various embodiments of the disclosure may be one of various types of electronic devices. The electronic devices may include, for example, a portable communication device (e.g., a smartphone), a computer device, a portable multimedia device, a portable medical device, a camera, a wearable device, or a home appliance. According to an embodiment of the disclosure, the electronic devices are not limited to those described above.

[0050] It should be appreciated that various embodiments of the disclosure and the terms used therein are not intended to limit the technological features set forth herein to particular embodiments and include various changes, equivalents, or replacements for a corresponding embodiment. With regard to the description of the drawings, similar reference numerals may be used to refer to similar or related elements. It is to be understood that a singular form of a noun corresponding to an item may include one or more of the things, unless the relevant context clearly indicates otherwise. As used herein, each of such phrases as “A or B,” “at least one of A and B,” “at least one of A or B,” “A, B, or C,” “at least one of A, B, and C,” and “at least one of A, B, or C,” may include any one of, or all possible combinations of the items enumerated together in a corresponding one of the phrases. As used herein, such terms as “1st” and “2nd,” or “first” and “second” may be used to simply distinguish a corresponding component from another, and does not limit the components in other aspect (e.g., importance or order). It is to be understood that if an element (e.g., a first element) is referred to, with or without the term “operatively” or “communicatively”, as “coupled with,” “coupled to,” “connected with,” or “connected to” another element (e.g., a second element), it means that the element may be coupled with the other element directly (e.g., wiredly), wirelessly, or via a third element.

[0051] As used in various embodiments of the disclosure, the term “module” may include a unit implemented in hardware, software, or firmware, and may interchangeably be used with other terms, for example, “logic,” “logic block,” “part,” or “circuitry”. A module may be a single integral component, or a minimum unit or part thereof, adapted to perform one or more functions. For example, according to an embodiment, the module may be implemented in a form of an application-specific integrated circuit (ASIC).

[0052] Various embodiments of the disclosure may be implemented as software (e.g., the program

140) including one or more instructions that are stored in a storage medium (e.g., internal memory **136** or external memory **138**) that is readable by a machine (e.g., the electronic device **101**). For example, a processor (e.g., the processor **120**) of the machine (e.g., the electronic device **101**) may invoke at least one of the one or more instructions stored in the storage medium, and execute it, with or without using one or more other components under the control of the processor. This allows the machine to be operated to perform at least one function according to the at least one instruction invoked. The one or more instructions may include a code generated by a compiler or a code executable by an interpreter. The machine-readable storage medium may be provided in the form of a non-transitory storage medium. Wherein, the term “non-transitory” simply means that the storage medium is a tangible device, and does not include a signal (e.g., an electromagnetic wave), but this term does not differentiate between where data is semi-permanently stored in the storage medium and where the data is temporarily stored in the storage medium.

[0053] According to an embodiment, a method according to various embodiments of the disclosure may be included and provided in a computer program product. The computer program products may be traded as commodities between sellers and buyers. The computer program product may be distributed in the form of a machine-readable storage medium (e.g., compact disc read only memory (CD-ROM)), or be distributed (e.g., downloaded or uploaded) online via an application store (e.g., Play Store™), or between two user devices (e.g., smart phones) directly. If distributed online, at least part of the computer program product may be temporarily generated or at least temporarily stored in the machine-readable storage medium, such as memory of the manufacturer's server, a server of the application store, or a relay server.

[0054] According to various embodiments, each component (e.g., a module or a program) of the above-described components may include a single entity or multiple entities. According to various embodiments, one or more of the above-described components may be omitted, or one or more other components may be added. Alternatively or additionally, a plurality of components (e.g., modules or programs) may be integrated into a single component. In such a case, according to various embodiments, the integrated component may still perform one or more functions of each of the plurality of components in the same or similar manner as they are performed by a corresponding one of the plurality of components before the integration. According to various embodiments, operations performed by the module, the program, or another component may be carried out sequentially, in parallel, repeatedly, or heuristically, or one or more of the operations may be executed in a different order or omitted, or one or more other operations may be added.

[0055] FIG. 2 is a front perspective view illustrating an electronic device according to various embodiments of the disclosure. FIG. 3 is a rear perspective view illustrating an electronic device according to various embodiments of the disclosure.

[0056] Referring to FIGS. 2 and 3, the electronic device **101** according to an embodiment may include a housing **310** including a front surface **310A**, a rear surface **310B**, and side surface **310C** surrounding a space defined between the front surface **310A** and the rear surface **310B**. In another embodiment (not shown), the housing **310** may refer to a structure that forms some of the front surface **310A** of FIG. 2, the rear surface **310B** and the side surface **310C** of FIG. 3. According to an embodiment, at least a portion of the front surface **310A** may be formed by a substantially transparent front plate **302** (e.g., a glass plate or a polymer plate including various coating layers). The rear surface **310B** may be formed by a rear plate **311**. The rear plate **311** may be formed of, for example, glass, ceramic, a polymer, or a metal (e.g., aluminum, stainless steel (STS), or magnesium), or a combination of two or more of these materials. The side surface **310C** may be formed by a side bezel structure (or a side member) **318** coupled to the front plate **302** and the rear plate **311** and including a metal and/or a polymer. In some embodiments, the rear plate **311** and the side bezel structure **318** may be integrally formed, and include the same material (e.g., a metal material or ceramic such as glass, and aluminum).

[0057] In the illustrated embodiment, the front plate **302** may include two first edge areas **310D**,

which seamlessly and with a bend extend from the front surface **310A** towards the rear plate **311**, on both the long edges of the front plate **302**. In the illustrated embodiment (see FIG. **3**), the rear plate **311** may include two second edge areas **310E**, which seamlessly and with a bend extend from the rear surface **310B** towards the front plate **302**, on both the long edges thereof. According to some embodiments, the front plate **302** (or the rear plate **311**) may include only one of the first edge areas **310D** (or the second edge areas **310E**). In another embodiment, some of the first edge areas **310D** or the second edge areas **310E** may not be included. In the above embodiments, when viewed from a side of the electronic device **101**, the side bezel structure **318** may have a first thickness (or width) for a side that does not include the first edge areas **310D** or the second edge areas **310E**, and may have a second thickness, which is thinner than the first thickness, for a side that includes the first edge areas **310D** or the second edge areas **310E**.

[0058] According to an embodiment, the electronic device **101** may include at least one or more of displays **330**, and **301**, audio modules **303**, **307**, and **314** (e.g., the audio module **170** of FIG. **1**), a sensor module (e.g., the sensor module **176** of FIG. **1**), camera modules **305**, **312**, and **313** (e.g., the camera module **180** of FIG. **1**), a key input device **317** (e.g., the input device **150** of FIG. **1**), and connector holes **308** and **309** (e.g., the connecting terminal **178** of FIG. **1**). In some embodiments, at least one of the components (e.g., the connector hole **309**) may be omitted from the electronic device **101**, or the electronic device **101** may additionally include other components.

[0059] According to an embodiment, the displays **330** and **301** may be visually exposed, for example, through a large portion of the front plate **302**. In some embodiments, at least a portion of the displays **330** and **301** may be exposed through the front plate **302** forming the front surface **310A** and the first edge areas **310D**. In some embodiments, the edges of the displays **330** and **301** may be formed to be substantially the same as the contour shape of the front plate **302** adjacent thereto. In another embodiment (not shown), the interval between the outer edge of the displays **330** and **301** and the outer edge of the front plate **302** may be substantially constant in order to enlarge the exposed area of the displays **330** and **301**.

[0060] According to an embodiment, the surface (or the front plate **302**) of the housing **310** may include a screen display area formed as the displays **330**, and **301** is visually exposed. For example, the screen display area may include the front surface **310A** and the first edge areas **310D**.

[0061] In another embodiment (not shown), the screen display area (e.g., the front surface **310A**, and the first edge area **310D**) of the displays **330**, and **301** may form a recess or an opening in a portion thereof, and may include at least one or more of the audio module **314**, the sensor module (not shown), the light-emitting element (not shown), and the camera module **305**, which is aligned with the recess or the opening. In another embodiment (not shown), at least one or more of the audio module **314**, the sensor module (not shown), the camera module **305**, the fingerprint sensor (not shown), and the light-emitting element (not shown) may be included on the rear surface of the screen display area of the displays **330**, and **301**. In another embodiment (not shown), the displays **330**, and **301** may be coupled to or disposed adjacent to a touch-sensing circuit, a pressure sensor capable of measuring the intensity of the touch (pressure), and/or a digitizer detecting a magnetic field type stylus pen. In some embodiments, at least part of the key input device **317** may be disposed in the first edge areas **310D** and/or the second edge areas **310E**.

[0062] According to an embodiment, the audio modules **303**, **307**, and **314** may include, for example, a microphone hole **303** and speaker holes **307** and **314**. The microphone hole **303** may include a microphone disposed therein to acquire external sound, and in some embodiments, a plurality of microphones may be disposed therein to be able to detect the direction of a sound. The speaker holes **307** and **314** may include an external speaker hole **307** and a phone call receiver hole **314**. In some embodiments, the speaker holes **307** and **314** and the microphone hole **303** are implemented as a single hole, or a speaker may be included without the speaker holes **307** and **314** (e.g., a piezo speaker). The audio modules **303**, **307**, and **314** are not limited to the above-described structure, and may be variously changed in design depending on the structure of the electronic

device **101**, for example, by mounting only some of the audio modules or by adding new audio modules.

[0063] According to an embodiment, the sensor modules (not shown) may generate an electrical signal or a data value corresponding to, for example, an internal operating state or external environmental state of the electronic device **101**. The sensor modules (not shown) may include, for example, a first sensor module (e.g., a proximity sensor) and/or a second sensor module (e.g., a fingerprint sensor) disposed on the front surface **310A** of the housing **310**, and/or a third sensor module (e.g., an HRM sensor) and/or a fourth sensor module (e.g., a fingerprint sensor) disposed on the rear surface **310B** of the housing **310**. In some embodiments (not shown), the fingerprint sensor may be disposed not only on the front surface **310A** of the housing **310** (e.g., the displays **330** and **301**), but also on the rear surface **310B**. The electronic device **101** may further include at least one of sensor modules, which are not shown, such as a gesture sensor, a gyro sensor, an atmospheric pressure sensor, a magnetic sensor, an acceleration sensor, a grip sensor, a color sensor, an infrared (IR) sensor, a biometric sensor, a temperature sensor, a humidity sensor, and an illuminance sensor. The sensor modules are not limited to the above-described structure, and may be variously changed in design depending on the structure of the electronic device **101**, for example, by mounting some of the sensor modules or by adding new sensor modules.

[0064] According to an embodiment, the camera modules **305**, **312**, and **313** may include, for example, a front camera module **305** disposed on the front surface **310A** of the electronic device **101**, and a rear camera module **312** and/or a flash **313** disposed on the rear surface **310B**. The camera modules **305** and **312** may include one or more lenses, an image sensor, and/or an image signal processor. The flash **313** may include, for example, a light-emitting diode or a xenon lamp. In some embodiments, two or more lenses (e.g., an infrared camera lens, a wide-angle lens, and a telephoto lens) and image sensors may be disposed on one surface of the electronic device **101**. The camera modules **305**, **312**, and **313** are not limited to the above-described structure, and may be variously changed in design depending on the structure of the electronic device **101**, for example, by mounting some of the camera modules or by adding new camera modules.

[0065] According to an embodiment, the electronic device **101** may include a plurality of camera modules (e.g., a dual camera or a triple camera) having different properties (e.g., angles of view) or functions, respectively. For example, a plurality of camera modules **305** and **312** including lenses having different angles of view may be configured, and the electronic device **101** may control the camera modules **305** and **312** to change the angles of view thereof executed therein based on a user's selection. For example, at least one of the plurality of camera modules **305** and **312** may be a wide-angle camera, and at least another one of the camera modules may be a telephoto camera. Similarly, at least one of the plurality of camera modules **305** and **312** may be a front camera, and at least another one of the camera modules may be a rear camera. In addition, the plurality of camera modules **305** and **312** may include at least one of a wide-angle camera, a telephoto camera, and an infrared (IR) camera (e.g., a time-of-flight (TOF) camera, or a structured light camera). According to an embodiment, the IR camera may be operated as at least a portion of a sensor module. For example, the TOF camera may be operated as at least a portion of a sensor module (not shown) for detecting a distance to a subject.

[0066] According to an embodiment, the key input device **317** may be disposed on the side surface **310C** of the housing **310**. In another embodiment, the electronic device **101** may not include some or all of the above-mentioned key input device **317**, and a key input device **317**, which is not included therein, may be implemented in another form such as a soft key on the display **301**. In some embodiments, the key input device may include a sensor module **316** disposed on the second surface (e.g., rear surface **310B**) of the housing **310**.

[0067] According to an embodiment, the light-emitting element (not shown) may be disposed on, for example, the front surface **310A** of the housing **310**. The light-emitting element (not shown) may provide, for example, state information of the electronic device **101** in the form of light. In

another embodiment, the light-emitting element (not shown) may provide a light source that interacts with, for example, the operation of the front camera module **305**. The light-emitting element (not shown) may include, for example, an LED, an IR LED, and a xenon lamp.

[0068] According to an embodiment, the connector holes **308** and **309** may include, for example, a first connector hole **309** capable of accommodating a connector (e.g., a USB connector) for transmitting/receiving power and/or data to/from an external electronic device, and/or a second connector hole **308** (e.g., an carphone jack) capable of accommodating a connector for transmitting/receiving an audio signal to/from an external electronic device.

[0069] According to an embodiment, some camera module **305** of the camera modules **305** and **312** and/or some sensor modules (not shown) of the sensor modules may be disposed to be exposed to the outside through at least a portion of the displays **330** and **301**. For example, the camera modules **305** may include a punch hole camera disposed inside a hole or recess formed on the rear surface of the displays **330** and **301**. According to an embodiment, the camera module **312** may be disposed inside the housing **310** such that the lens is exposed to the second surface (e.g., rear surface **310B**) of the electronic device **101**. For example, the camera modules **312** may be disposed on a printed circuit board (e.g., the printed circuit board **340** of FIG. 4).

[0070] According to an embodiment, the camera module **305** and/or the sensor module may be disposed from the internal space of the electronic device **101** to the front plate **302** of the displays **330**, and **301** to come into contact with the external environment through a transparent area. In addition, some sensor modules **304** may be disposed in the internal space in the electronic device to implement the functions thereof without being visually exposed through the front plate **302**.

[0071] FIG. 4 is an exploded perspective view illustrating an electronic device according to various embodiments.

[0072] Referring to FIG. 4, the electronic device **101** (e.g., the electronic device **101** of FIGS. 1 to 3) according to various embodiments may include a support bracket **370**, a front plate **320** (e.g., the front plate **302** of FIG. 2), displays **330** (e.g., the display **301** of FIG. 2), a printed circuit board **340** (e.g., a PCB, flexible PCB (FPCB), or a rigid flexible PCB (RFPCB)), a battery **350** (e.g., the battery **189** of FIG. 1), a second support member **360** (e.g., the rear structure), an antenna (not shown) (e.g., the antenna module **197** of FIG. 1), and a rear plate **380** (e.g., the rear plate **311** of FIG. 2). The electronic device **101** may further include a camera module **312** that includes a camera assembly **312a** and a camera deco **315**, a fixing member **410**, and a conductive member **420**. The support bracket **370** of the electronic device **101** according to an embodiment may include a side bezel structure **371** (e.g., the side bezel structure **318** of FIG. 2) and a first support member **372**.

[0073] In some embodiments, in the electronic device **101**, at least one of the components (e.g., the first support member **372** or the second support member **360**) may be omitted, or other components may be additionally included. At least one of the components of the electronic device **101** may be the same as or similar to at least one of the components of the electronic device **101** in FIG. 2 or FIG. 3, and a redundant description thereof will be omitted below.

[0074] According to various embodiments, the first support member **372** may be disposed in the electronic device **101** to be connected to the side bezel structure **371**, or may be integrated with the side bezel structure **371**. The first support member **372** may be formed of, for example, a metal material and/or a non-metal material (e.g., a polymer). The display **330** may be coupled to one surface of the first support member **332**, and the printed circuit board **340** may be coupled to the other surface of the first support member **332**.

[0075] According to various embodiments, on the printed circuit board **340**, a processor, a memory, and/or an interface may be mounted. The processor may include various processing circuitry including, for example, one or more of, for example, a central processing unit, an application processor, a graphics processor, an image signal processor, a sensor hub processor, or a communication processor. According to various embodiments, the printed circuit board **340** may include a flexible printed circuit board type radio frequency cable (FRC). For example, the printed

circuit board **340** may be disposed on at least a portion of the first support member **372**, and may be electrically connected to an antenna module (e.g., the antenna module **197** of FIG. **1**) and a communication module (e.g., the communication module **190** of FIG. **1**).

[0076] According to an embodiment, the memory may include, for example, a volatile memory or a nonvolatile memory.

[0077] According to an embodiment, the interface may include, for example, a high-definition multimedia interface (HDMI), a universal serial bus (USB) interface, an SD card interface, and/or an audio interface. The interface may electrically or physically connect, for example, the electronic device **101** to an external electronic device, and may include a USB connector, an SD card/an MMC connector, or an audio connector.

[0078] According to various embodiments, the battery **350**, which is a device for supplying power to at least one component of the electronic device **101**, may include, for example, a non-rechargeable primary battery, a rechargeable secondary battery, or a fuel cell. At least a portion of the battery **350** may be disposed on substantially the same plane as, for example, the printed circuit board **340**. The battery **350** may be integrally disposed inside the electronic device **101**, or may be detachably disposed on the electronic device **101**.

[0079] According to various embodiments, the second support member **360** (e.g., the rear structure) may be disposed between the printed circuit board **340** and the antenna. For example, the second support member **360** may include one surface to which at least one of the printed circuit board **340** or the battery **350** is coupled, and the other surface to which the antenna is coupled.

[0080] According to various embodiments, the antenna (not shown) may be disposed between the rear plate **380** and the display **350**. The antenna may include, for example, a near field communication (NFC) antenna, a wireless charging antenna, and/or a magnetic secure transmission (MST) antenna. The antenna may perform short-range communication with, for example, an external electronic device, or may wirelessly transmit/receive power that is required for charging to/from the external device. In another embodiment, an antenna structure may be included with a part of the side bezel structure **371** and/or the first support member **372**, or a combination thereof.

[0081] According to various embodiments, the rear plate **380** may form at least a portion of the rear surface (e.g., the second surface **310B** of FIG. **3**) of the electronic device **101**.

[0082] According to various embodiments, the fixing member **410** may be coupled to the second support member **360**, and the conductive member **420** may be positioned between the fixing member **410** and the camera deco. Hereinafter, the contact structure of the camera module including the fixing member **410** and the conductive member **420** will be described in detail.

[0083] FIG. **5** is an exploded perspective view illustrating a support bracket, a rear plate, and a camera deco connected to the rear plate in an electronic device, according to one of various embodiments of the disclosure.

[0084] FIG. **6** is an exploded perspective view enlarging area A of FIG. **5**.

[0085] According to various embodiments, the electronic device (e.g., the electronic device **101** of FIGS. **1** to **4**) may include a housing (e.g., the housing **310** of FIGS. **2** and **3**) and a rear structure **360** disposed in the housing **310** (e.g., the second support member **360** of FIG. **4**), a camera module **312**, and a printed circuit board **340**.

[0086] According to an embodiment, a camera module (e.g., the camera module **312** of FIG. **3**) includes a camera assembly **312a** including one or more lenses, an image sensor, and/or an image signal processor, and a camera deco **315** covering the camera assembly **312a**. According to another embodiment, the housing **310** may include the rear plate **380** covering the rear surface of the electronic device **101**, and the camera deco **315** covering the camera assembly (e.g., the camera module **312** of FIG. **3**), and at least partially forming the rear surface of the electronic device **101**. The housing **310** may further include the support bracket **370** providing a mounting space for the side components and internal components of the electronic device **101**.

[0087] The configurations of the housing **310**, the camera module **312**, the rear structure **360**, and

the printed circuit board **340** of FIGS. **5** and **6** may be partially or entirely the same as those of the housing **310**, and the camera module **312** of FIGS. **2** and **3**, the rear structure **360**, and the printed circuit board **340** of FIG. **4**.

[0088] According to various embodiments, the rear surface (e.g., the surface facing the +Z axis) of the housing **310** may be formed by the first surface **311b** of the rear plate **380** and the camera deco **315** of the camera module **312**. According to an embodiment, the rear plate **380** may include the first surface **311b** and an opening **311a** formed in an area (e.g., an edge adjacent area) of the first surface **311b**. The camera deco **315** has a shape corresponding to the shape of the opening **311a** such that the edge area thereof may be fitted in the opening **311a**, and may be at least partially exposed to the outside of the opening **311a** (e.g., in the +Z-axis direction). According to an embodiment, the camera deco **315** may be designed to have a different thickness compared to the adjacent opening **311a**. As another example, when the rear plate **380** is formed of a metal material, the camera deco **315** may be electrically connected to the rear plate **380** via a direct contact.

[0089] According to various embodiments, the camera deco **315** is a separate configuration isolated from the rear plate **380** and may include a metal material (e.g., aluminum). The camera deco **315** may include at least one opening **315e** corresponding to the number of lens assemblies of the camera module **312** and reduce an external impact transmitted to the camera module **312**, thereby protecting the camera module **312**.

[0090] According to various embodiments, the printed circuit board **340** may be disposed in one area of the support bracket **370** of the housing **310** and a battery (e.g., the battery **350** of FIG. **4**) may be disposed in the other area thereof. For example, the camera module **312** may be disposed on one side of the printed circuit board **340**, the battery may be disposed on the other side thereof, and the camera module **312** and/or the battery may be electrically connected to the printed circuit board **340**.

[0091] According to various embodiments, the rear structure **360** may be positioned between the rear plate **380** and the printed circuit board **340**. One area of the rear structure **360** may cover the printed circuit board **340**, and the other area thereof may cover a part of the camera assembly **312a**. For example, the rear structure **360** may substantially cover most of the surfaces facing the second direction (−Z-axis direction) of the printed circuit board **340**. Accordingly, the rear structure **360** may support the camera assembly **312a** and/or the printed circuit board **340** so as not to move due to an external impact.

[0092] According to an embodiment, the rear structure **360** may be provided as an injection molding (e.g., a non-conductive material), and forms a conductive pattern (not shown) to be used as an antenna radiator on one area thereof (e.g., a surface facing the second direction (−Z-axis direction)). The conductive pattern may be a laser direct structuring (LDS) pattern, and may be formed of a conductive material including a metal material such as copper or nickel. For example, the laser direct structuring (LDS) pattern may be formed through a plating and coating process after selectively processing the pattern using a laser on an injection product (e.g., a material including a thermoplastic resin). Through laser processing, it is possible to facilitate the plating of metal materials on the rough resin surface in the micro scale.

[0093] According to various embodiments, the electronic device **101** may include a fixing member **410** and a conductive member **420** which are disposed adjacent to the camera module **312**. The fixing member **410** and/or the conductive member **420** may provide a discharge path for improving electrostatic discharge (ESD) of the camera module **312**.

[0094] According to various embodiments, the fixing member **410** may be coupled to the rear structure **360** to fix the camera assembly **312a** and/or the printed circuit board **340** to the support bracket **370**. For example, the fixing member **410** includes a fastening structure such as a screw, and one surface of the fixing member **410** facing the second direction (−Z-axis direction) is disposed to face the camera deco **315** and/or the conductive member **420**, and the other part (e.g., a part including a threaded screw) of the fixing member **410** may be inserted and fixed to the rear

structure **360** and the support bracket **370**.

[0095] According to various embodiments, the conductive member **420** may be disposed between the fixing member **410** and the camera deco **315** to electrically connect the fixing member **410** and the camera deco **315**. For example, the conductive member **420** may be made of a material including elasticity and conductivity. The specified compression and tensile rates provided by the fixing member **410** may prevent a lifting phenomenon between the camera deco **315** and the rear structure **360**. The conductive member **420** may form a part of a discharge path for improving electrostatic discharge (ESD) by providing a structure electrically connected to the fixing member **410** and/or the camera deco **315**.

[0096] FIG. **7** is a view illustrating a support bracket and a rear structure coupled on the support bracket in a state in which the rear plate of the electronic device is removed, according to one of various embodiments of the disclosure.

[0097] FIG. **8A** is a view illustrating a side of the camera deco viewed in one direction, according to one of various embodiments of the disclosure.

[0098] FIG. **8B** is a view illustrating another side of a camera deco viewed in another direction, according to one of various embodiments of the disclosure.

[0099] According to various embodiments, the electronic device (e.g., the electronic device **101** of FIGS. **1** to **4**) may include the support bracket **370**, the rear structure **360**, the camera module (e.g., the camera module **312** of FIG. **3**), the printed circuit board **340**, the fixing member **410**, and the conductive member **420**. According to an embodiment, the camera module (e.g., the camera module **312** of FIG. **3**) may include a camera assembly **312a** including one or more lenses, an image sensor, and/or an image signal processor, and the camera deco **315** covering the camera assembly **312a**.

[0100] The configurations of the support bracket **370**, the rear structure **360**, the printed circuit board **340**, the fixing member **410**, and the conductive member **420** of FIGS. **7** to **8B** are partially or entirely the same as those of the support bracket **370**, the rear structure **360**, the printed circuit board **340**, the fixing member **410**, and the conductive member **420** of FIGS. **5** and **6**.

[0101] According to various embodiments, the fixing member **410** may be positioned in a first area **S1** of the rear structure **360**. For example, the rear structure **360** may provide a hole including a threaded screw in the first area **S1** thereof, and the fixing member **410** may be inserted (e.g., fastened) into the hole. The fixing member **410** may fix the rear structure **360** to a portion of the rear structure **360** and/or the camera assembly **312a** together with other surrounding fixing members.

[0102] According to various embodiments, the camera deco **315** may include a first surface **315a** facing the inside of the electronic device **101** and a second surface **315b** formed to be exposed to the outside of the electronic device **101**. According to an embodiment, the conductive member **420** may be positioned in a second area **S2** of the first surface **315a** of the camera deco **315**. For example, the second area **S2** of the camera deco **315** is provided to form a recess having a size corresponding to that of the conductive member **420**, and the conductive member **420** inserted into the recess may stably maintain contact with the fixing member **410**. As another example, an adhesive member (e.g., a tape or a bond) may be disposed on one surface of the conductive member **420**, or a bonding force between the conductive member **420** and the camera deco **315** may be strengthened.

[0103] According to various embodiments, when viewed from above the camera deco **315** (e.g., when viewed by projecting the camera deco **315**), a portion of the first area **S1** of the rear structure **360** may be overlapped with the second area **S2** of the camera deco **315**. According to another embodiment, when viewed from above the camera deco **315** (e.g., when viewed by projecting the camera deco **315**), a portion of the second area **S2** of the camera deco **315** may be disposed to be overlapped with the first area **S1** of the rear structure **360**. The conductive member **420** and the fixing member **410** may each include surfaces in contact with each other, and may electrically

connect the camera deco **315** and the support bracket **370** to each other.

[0104] In the contact structure of the camera module according to the disclosure, the conductive member **420** may be provided as a contact structure for improving ESD, serving as a fastening structure for fixing the rear structure **360** to the electronic device **101**. Accordingly, a contact structure requiring a separate space in one area of the printed circuit board **340** may be excluded, and thus it is possible to secure an additional mounting space of the electronic device **101** and to provide a degree of freedom in design.

[0105] FIG. **9** is a view illustrating a support bracket and a rear structure coupled on the support bracket in an electronic device, viewed by projecting a rear plate, according to one of various embodiments of the disclosure.

[0106] FIG. **10** is an enlarged projection view of area B of FIG. **9**.

[0107] FIG. **11** is a cross-sectional view taken along line L-L' of FIG. **11**.

[0108] According to various embodiments, the electronic device (e.g., the electronic device **101** of FIGS. **1** to **4**) may include the display **330**, the rear plate **380**, the support bracket **370**, the rear structure **360**, and the camera module (e.g., the camera module **312** of FIG. **3**), the printed circuit board **340**, the fixing member **410**, and the conductive member **420**. According to one embodiment, the camera module (e.g., the camera module **312** of FIG. **3**) may include the camera assembly **312a** including one or more lenses, an image sensor, and/or an image signal processor, and the camera deco **315** covering the camera assembly **312a**.

[0109] The configurations of the display **330** and the rear plate **380** of FIGS. **9** to **11** may be partially or entirely the same as those of the display **330** and the rear plate **380** of FIG. **4**. The configurations of the support bracket **370**, the rear structure **360**, the printed circuit board **340**, the fixing member **410**, and the conductive member **420** of FIGS. **9** to **11** may be partially or entirely the same as those of the support bracket **370**, the rear structure **360**, the printed circuit board **340**, the fixing member **410**, and the conductive member **420** of FIGS. **5** to **8B**.

[0110] According to various embodiments, when viewed from the rear surface of the electronic device **101** (e.g., when viewed toward the rear plate **380**), the conductive member **420** and the fixing member **410** may be disposed along the first direction (+Z-axis direction) with respect to the camera deco **315**. The rear structure **360** and the support bracket **370** may be positioned along the edge of the fixing member **410**, and the printed circuit board **340** may be positioned in an area adjacent to the support bracket **370**.

[0111] According to various embodiments, the fixing member **410** may form a discharge path L between the camera deco **315** and the support bracket **370** in order to prevent the camera module **312** from being damaged due to static electricity. For example, the discharge path L may be formed to discharge static electricity generated in the electronic device **101** (or the camera module **312**) along the camera deco **315**, the conductive member **420**, the fixing member **410**, the support bracket **370** and the printed circuit board **340**.

[0112] According to an embodiment, the conductive member **420** attached to an area of the camera deco **315** may be designed to be in direct contact with the fixing member **410** so that static electricity can be discharged.

[0113] According to an embodiment, the fixing member **410** may be disposed to be in contact with a plurality of components. Since the rear structure **360** for supporting the camera module **312** and/or the printed circuit board **340** is formed of an injection molding material, the fixing member **410** cannot directly provide a conductive path. Accordingly, the fixing member **410** passes through the rear structure **360** and is formed to be in direct contact with the support bracket **370** formed of a conductive member, thereby providing a path.

[0114] For example, the fixing member **410** may include a first portion **411** for electrically connecting to the camera deco **315** (or the conductive member **420**), a second portion **412** for coupling with the rear structure **360**, and a third portion **413** coupled to the support bracket **370** and provided for electrical connection. The first portion **411** may be one surface facing the second

direction (-Z-axis direction) of the fixing member **410** to directly form a contact point with the conductive member **420**. As the second portion **412**, which is an extension portion for connecting the first portion **411** and the third portion **413**, is formed to penetrate the rear structure **360** (e.g., a non-metal structure), it is possible to electrically connect the metal structures (e.g., the camera deco **315** and the support bracket **370**) separated by the non-metal structure. The third portion **413** is disposed in contact with the support bracket **370** to extend the discharge path L formed along the first portion **411**, the second portion **412**, and the third portion **413** to the support bracket **370**.

[0115] According to various embodiments, the printed circuit board **340** may be electrically connected to the support bracket **370**. For example, the printed circuit board **340** may be disposed on one area of the support bracket **370** via a direct contact. In another example, as the printed circuit board **340** is disposed adjacent to and spaced apart from one area of the support bracket **370**, electrical flow may be provided by means of coupling. As a result, it is possible that static electricity may be discharged through the ground of the printed circuit board **340**.

[0116] In the contact structure of the camera module according to the disclosure, the conductive member **420** may be provided as a contact structure for improving the ESD, serving as a fastening structure for fixing the rear structure **360** to the electronic device **101**. Accordingly, since a contact structure requiring a separate space in one area of the printed circuit board **340** may be excluded, it is possible to secure an additional mounting space of the electronic device **101** and provide a degree of freedom in design.

[0117] An electronic device (e.g., the electronic device of FIGS. **1** to **4**) according to various embodiments of the disclosure may include a housing (e.g., **310** of FIG. **5**) including a rear plate (e.g., **380** of FIG. **5**) including an opening (e.g., **311a** of FIG. **5**) and a support bracket (e.g., **370** of FIG. **5**) at least partially disposed along an edge of the rear plate; a camera deco (e.g., **315** of FIG. **5**) disposed in the opening to be exposed to the outside, the camera deco covering a camera assembly (e.g., **312a** of FIG. **5**) and connected to the rear plate; a printed circuit board (e.g., **340** of FIG. **5**) disposed in the housing; a rear structure (e.g., **360** of FIG. **5**) supporting the camera assembly and the printed circuit board; a fixing member (e.g., **410** of FIG. **5**) coupled to the rear structure and fixing the camera assembly and/or the printed circuit board to the support bracket; and a conductive member (e.g., **420** of FIG. **5**) at least partially disposed between the camera deco and the fixing member to electrically connect the camera deco and the fixing member.

[0118] According to various embodiments, at least a portion of the fixing member and the conductive member may be disposed in contact with each other.

[0119] According to various embodiments, the fixing member may be disposed to extend to the inside of the support bracket through a portion of the rear structure.

[0120] According to various embodiments, the electronic device may be configured to form a discharge path from the camera assembly to the printed circuit board through the camera deco, the conductive member, the fixing member electrically connected to the conductive member, and the support bracket.

[0121] According to various embodiments, the fixing member may comprise a first portion (e.g., **411** of FIG. **11**) disposed to form a contact point with the camera deco or the conductive member, a second portion (e.g., **412** of FIG. **11**) for coupling with the rear structure, and a third portion (e.g., **413** of FIG. **11**) coupled to the support bracket and provided for electrical connection between the support bracket and the camera deco.

[0122] According to various embodiments, the fixing member may be a fastening member including a threaded screw for coupling the support bracket and the rear structure.

[0123] According to various embodiments, the conductive member may be disposed in contact with the camera deco and is compressed by being pressed by the fixing member to thereby restrict the formation of a gap between the conductive member and the camera deco.

[0124] According to various embodiments, the inside of the camera deco may include a recess and at least a portion of the conductive member may be disposed in the recess.

[0125] According to various embodiments, the conductive member may be disposed adjacent to an edge of the camera deco and formed to protrude in a direction opposite to the rear plate.

[0126] According to various embodiments, the conductive member may include an elastic material.

[0127] According to various embodiments, the printed circuit board may be disposed adjacent to the support bracket.

[0128] According to various embodiments, at least a portion of the printed circuit board may be formed to surround at least a portion of the fixing member.

[0129] According to various embodiments, the printed circuit board may be spaced apart from the conductive member.

[0130] According to various embodiments, the support bracket comprises a first area and a second area partitioned from the first area, wherein the camera assembly and the printed circuit board may be disposed in the first area and the battery may be disposed in the second area.

[0131] According to various embodiments, the electronic device may further comprise a display (e.g., **330** of FIG. **4**) disposed in the housing and disposed to face a direction opposite to the rear plate, and a battery (e.g., **350** of FIG. **4**) disposed in an area partitioned from the printed circuit board.

[0132] An electronic device (e.g., the electronic device **101** of FIGS. **1** to **4**) according to various embodiments of the disclosure may include a housing (e.g., **310** of FIG. **5**) that includes a rear plate (e.g., **380** of FIG. **5**) including an opening; and a camera deco (e.g., **315** of FIG. **5**) disposed in the opening to be exposed to the outside and connected to the rear plate; a support member (e.g., the first support member **372** of FIG. **4**) disposed in the housing; a printed circuit board (e.g., **340** of FIG. **5**) disposed in one area of the support member; a camera assembly (e.g., **312a** of FIG. **5**) covered by the camera deco and configured to capture an external object through at least one opening formed in the camera deco; a fixing member (e.g., **410** of FIG. **5**) configured to fix the camera assembly and/or the printed circuit board to the support bracket; and a conductive member at least partially disposed between the camera deco and the fixing member to electrically connect the camera deco and the fixing member.

[0133] According to various embodiments, the electronic device may further comprise a rear structure (e.g., **360** of FIG. **5**) supporting the camera assembly and the printed circuit board, wherein the fixing member is coupled to the rear structure to fix the camera assembly and/or the printed circuit board to the support member.

[0134] According to various embodiments, at least a portion of the fixing member and the conductive member may be disposed to be in contact with each other.

[0135] According to various embodiments, the fixing member may be disposed to extend through a portion of the rear structure to the inside of the support bracket.

[0136] According to various embodiments, the electronic device may form a discharge path facing from the camera assembly to the printed circuit board through the camera deco, the conductive member, the fixing member electrically connected to the conductive member, and the support bracket.

[0137] It will be apparent to one of ordinary skill in the art that the contact structure of the camera module and the electronic device comprising the same according to the disclosure as described above are not limited to the above-described embodiments and those shown in the drawings, and various changes, modifications, or alterations may be made thereto without departing from the scope of the present invention.

Claims

1. An electronic device, comprising: a housing comprising a rear plate including an opening and a support bracket at least partially disposed along an edge of the rear plate; a camera deco disposed in the opening to be exposed to an outside, the camera deco covering a camera assembly and

connected to the rear plate; a printed circuit board disposed in the housing; a rear structure supporting the camera assembly and the printed circuit board; a fixing member coupled to the rear structure and fixing the camera assembly and/or the printed circuit board to the support bracket; and a conductive member at least partially disposed between the camera deco and the fixing member to electrically connect the camera deco and the fixing member.

2. The electronic device of claim 1, wherein at least a portion of the fixing member and the conductive member are disposed to be in contact with each other.

3. The electronic device of claim 2, wherein the fixing member is disposed to extend to an inside of the support bracket through a portion of the rear structure.

4. The electronic device of claim 2, wherein the electronic device is configured to form a discharge path from the camera assembly to the printed circuit board through the camera deco, the conductive member, the fixing member electrically connected to the conductive member, and the support bracket.

5. The electronic device of claim 2, wherein the fixing member comprises: a first portion disposed to form a contact point with the camera deco or the conductive member; a second portion for coupling with the rear structure; and a third portion coupled to the support bracket and provided for electrical connection with the support bracket and the camera deco.

6. The electronic device of claim 2, wherein the fixing member is a fastening member including a threaded screw for coupling the support bracket and the rear structure.

7. The electronic device of claim 2, wherein the conductive member is disposed to be in contact with the camera deco and is compressed by being pressed by the fixing member to thereby restrict the formation of a gap between the conductive member and the camera deco.

8. The electronic device of claim 2, wherein an inside of the camera deco comprises a recess and at least a portion of the conductive member is disposed in the recess.

9. The electronic device of claim 2, wherein the conductive member is disposed adjacent to an edge of the camera deco and formed to protrude in a direction opposite to the rear plate.

10. The electronic device of claim 2, wherein the conductive member comprises an elastic material.

11. The electronic device of claim 2, wherein the printed circuit board is disposed adjacent to the support bracket.

12. The electronic device of claim 11, wherein at least a portion of the printed circuit board is formed to surround at least a portion of the fixing member.

13. The electronic device of claim 11, wherein the printed circuit board is spaced apart from the conductive member.

14. The electronic device of claim 1, wherein the support bracket comprises a first area and a second area partitioned from the first area, and wherein the camera assembly and the printed circuit board are disposed in the first area and a battery is disposed in the second area.

15. The electronic device of claim 1, further comprising: a display disposed in the housing, facing a direction opposite to the rear plate; and a battery disposed in an area partitioned from the printed circuit board.

16. An electronic device, comprising: a housing comprising a rear plate including an opening and a camera deco disposed in the opening to be exposed to the outside and connected to the rear plate; a support member disposed in the housing; a printed circuit board disposed in one area of the support member; a camera assembly covered by the camera deco and configured to capture an external object through at least one opening formed in the camera deco; a fixing member configured to fix the camera assembly and/or the printed circuit board to the support bracket; and a conductive member at least partially disposed between the camera deco and the fixing member to electrically connect the camera deco and the fixing member.

17. The electronic device of claim 16, wherein the electronic device further comprising: a rear structure supporting the camera assembly and the printed circuit board, wherein the fixing member is coupled to the rear structure to fix the camera assembly and/or the printed circuit board to the

support member.

18. The electronic device of claim 16, wherein at least a portion of the fixing member and the conductive member is disposed to be in contact with each other.

19. The electronic device of claim 17, wherein the fixing member is disposed to extend through a portion of the rear structure to the inside of the support bracket.

20. The electronic device of claim 17, wherein the electronic device is configured to form a discharge path from the camera assembly to the printed circuit board through the camera deco, the conductive member, the fixing member electrically connected to the conductive member, and the support bracket.
